Physics of X-ray Sources

Char. X-Rays: $E_x = h \cdot v = h \cdot c / \lambda = \Delta E_{kin} = E_{kin}(i) - E_{kin}(f)$









<u>XRD</u>

Introduction

Motivation

- X-ray diffraction is used to obtain structural information about crystalline solids.
- Useful in biochemistry to solve the 3D structures
 of complex bio-molecules.
- Bridge between physics, chemistry, and biology.
- X-ray diffraction is important for
 - Solid-state physics
 - Biophysics
 - Medical physics
 - Chemistry and Biochemistry



Spectrum of Electromagnetic Radiation						
Region	Wavelength (Angstroms)	Wavelength (centimeters)	Frequency (Hz)	Energy (eV)		
Radio	> 109	> 10	< 3 x 10 ⁹	< 10 ⁻⁵		
Microwave	10 ⁹ - 10 ⁶	10 - 0.01	3 x 10 ⁹ - 3 x 10 ¹²	10 ⁻⁵ - 0.01		
Infrared	$10^{6} - 7000$	0.01 - 7 x 10 ⁻⁵	3 x 10 ¹² - 4.3 x 10 ¹⁴	0.01 - 2		
Visible	7000 - 4000	7 x 10 ⁻⁵ - 4 x 10 ⁻⁵	4.3 x 10 ¹⁴ - 7.5 x 10 ¹⁴	2 – 3		
Ultraviolet	4000 - 10	4 x 10 ⁻⁵ - 10 ⁻⁷	7.5 x 10 ¹⁴ - 3 x 10 ¹⁷	3 - 10 ³		
X-Rays	10 - 0.1	10 ⁻⁷ - 10 ⁻⁹	3 x 10 ¹⁷ - 3 x 10 ¹⁹	10 ³ - 10 ⁵		
Gamma Rays	< 0.1	< 10 ⁻⁹	> 3 x 10 ¹⁹	> 10 ⁵		
Clamma UV IB Microwave						
	X-Rays	H	· · · · · · · · · · · · · · · · · · ·	Radio		
		H	³ 10 ⁻¹ 10	Radio 10 ³		

<u>XRD</u> **History of X-Ray Diffraction** 1895 X-rays discovered by Roentgen 🅵 1914 First diffraction pattern of a crystal made by Knipping and von Laue 1915 Theory to determine crystal structure from diffraction pattern developed by Bragg. 1953 DNA structure solved by Watson Diffraction improved by computer Now technology; methods used to determine atomic structures and in medical applications



The first X-ray

XRD X-ray Production High voltage When high energy electrons -**|**||+ strike an anode in a sealed vacuum, x-rays are Vacuum generated. Anodes are often made of copper, iron E Л 4 or molybdenum. Copper rod Filament Filament Tungsten voltage • X-rays are electromagnetic target radiation. They have enough energy electrons x-ravs to cause ionization. (a)

XRD

What is X-ray Diffraction (XRD)

- Most useful in the characterisation of crystalline materials; Ceramics, intermetallics, minerals, inorganic
- rapid and nondestructive techniques
- Provide dimension



XRD Components X-ray source Device for restricting wavelength range "goniometer" Divergence slit Sample holder X-ray Radiation detector Mask source Signal processor and readout Figure 11: A schematic drawing of a diffractometer











XRD



<u>XRD</u>

Single Crystal X-ray Diffraction

- Used to determine
 - crystal structure
 - orientation
 - degree of crystalline perfection/imperfections
 (twinning, mozaicity, etc.)
- Sample is illuminated with monochromatic radiation
 - Easier to index and solve the crystal structure because it diffraction peak is uniquely resolved

<u>XRD</u>

X-ray Powder Diffraction

- More appropriately called polycrystalline X-ray diffraction, because it can also be used for sintered samples, metal foils, coatings and films, finished parts, etc.
- Used to determine
- phase composition (commonly called phase ID)- what phases are present?
- quantitative phase analysis- how much of each phase is present?
- unit cell lattice parameters, crystal structure
- average crystallite size of nanocrystalline samples
- crystallite microstrain and texture
- residual stress (really residual strain)



<u>XRD</u>

Applications of X-Ray Diffraction

- Determination of Crystal structure
- Output Phase identification / transition
- Grain size / micro-strain
- Texture/stress(i.e.polymer , fiber)
- Determination of thin film composition
- Industry Identification of archeological materials

Advantages of XRD

XRD

- Fast identification of materials,
- Easy sample preparation,
- Computer-aided material identification,
- Large library of known crystalline structures.

<u>XRD</u>

Safety in XRD

- Exposure types
 - Short-term high-dose
 - Long-term low-dose
- Invisible, odorless, colorless
- (most exposures undetectable)
- Lab users must understand radiation safety issues and pass an exam to use lab
- Safeguards present in lab do not substitute for knowledge and following safe procedures



<u>XRD</u>

Summary & Conclusion

- X-ray diffraction is a technique for analyzing structures of biological molecules
- X-ray beam hits a crystal, scattering the beam in a manner characterized by the atomic structure
- Even complex structures can be analyzed by x-ray diffraction, such as DNA and proteins
- This will provide useful in the future for combining knowledge from physics, chemistry, and biology





X-ray energy E > Binding energy Eb





ex) Flame reaction The color (energy) is unique to element

<u>XRF</u>





XRF

How to measure E and I of the fluorescence X-rays.



Procedure of X-ray fluorescence Analysis (XRF)					
1. Check the chemical composition for samplesQualitative Analysis	$\begin{array}{c} & & & & & & & & & & & & & & & & & & &$				
2. Select the best condition for XRF analyses Combination of X-ray source, Detector, measurement time, etc.	Energy / eV				
3. Make calibration curve from standards	D Contraction of the second se				

<u>XRF</u>

XRF Calibration curves: 8 rock reference Cs 0.8 1.5 L Counts (RF 10 15 20 . 30 ergy (keV)

Probes used

-

Visible light

- Optical microscopy (OM)
- X-ray X-ray diffraction (XD)
- X-ray photo electron spectroscopy (XPS) _
- Neutron
- Neutron diffraction (ND) lon
- Secondary ion mass spectrometry (SIMS)
- Cleaning and thinning samples

Electron Scanning electron microscopy (SEM)

50 100 150 20 Concentration (ppm) Calibration Curve for Cd

R₂=0.9996, LLD=3.5 (ppm)

300

- Transmission electron microscopy (TEM)
- Electron holography (EH)
- Electron diffraction (ED) Electron energy loss spectroscopy
- (EELS) _
- Energy dispersive x-ray spectroscopy (EDS) Auger electron spectroscopy (AES)

SEM - TEM



Electron Microscopy

Introduction and History

o Electron microscopes are scientific instruments that use a beam of energetic electrons to examine objects on a very fine scale.

Electron microscopes were developed due to the limitations of Light Microscopes which are limited by the physics of light.

 $_{
m O}$ In the early 1930's this theoretical limit had been reached and there was a scientific desire to see the fine details of the interior structures of organic cells (nucleus, mitochondria...etc.).

This required 10,000x plus magnification which was not possible using current optical microscopes.

SEM - TEM

Comparison of OM, TEM and SEM



Principal features of an optical microscope, a transmission electron microscope and a scanning electron microscope, drawn to emphasize the similarities of overall design.

SEM - TEM







SEM - scanning electron microscopy

 $\lambda = h/(2m_{electron}qV_o + q^2Vo^2/c^2))^{1/2}$

Effects of increasing voltage in electron gun:

Resolution increased (). decreased)

Penetration increases

(insulators)

Specimen charging increases



Specimen damage increases

Image contrast decreases

SEM - scanning electron microscopy

Scanning electron microscopy is used for inspecting topographies of specimens at very high magnifications using a piece of equipment called the scanning electron microscope. SEM magnifications can go to more than 300,000 X but most semiconductor manufacturing applications require magnifications of less than 3,000 X only. SEM inspection is often used in the analysis of die/package cracks and fracture surfaces, bond failures, and physical defects on the die or package surface.

During SEM inspection, a beam of electrons is focused on a spot volume of the specimen, resulting in the transfer of energy to the spot. These bombarding electrons, also referred to as primary electrons, dislodge electrons from the specimen itself. The dislodged electrons, also known as secondary electrons, are attracted and collected by a positively biased grid or detector, and then translated into a signal.

To produce the SEM image, the electron beam is swept across the area being inspected, producing many such signals. These signals are then amplified, analyzed, and translated into images of the topography being inspected. Finally, the image is shown on a CRT.

SEM - scanning electron microscopy

- The energy of the primary electrons determines the quantity of secondary electrons collected during inspection. The emission of secondary electrons from the specimen increases as the energy of the primary electron beam increases, until a section of the primary electron becameration of the primary section of the primary beam is a section of the primary beam is increased, because the primary beam is already activating electrons deep below the surface of the specimen. Electrons coming from such depths usually recombine before reaching the surface for emission.
- Aside from secondary electrons, the primary electron beam results in the emission of backscattered (or reflected) electrons from the specimen. Backscattered electrons possess more energy than secondary electrons, and have a definite direction. As such, they can not be collected by a secondary electron detector, unless the detector is directly in their path of travel. All emissions above 50 eV are considered to be backscattered electrons.

SEM - scanning electron microscopy

- Backscattered electron imaging is useful in distinguishing one material from another, since the yield of the collected backscattered electrons increases monotonically with the specimen's atomic number. Backscatter imaging can distinguish elements with atomic number differences of at least 3, i.e., materials with atomic number differences of at least 3 would appear with good contrast on the image. For example, inspecting the remaining Au on an Al bond pad after its Au ball bond has lifted off would be easier usin backscatter imaging, since the Au islets would stand out from the Al background.
- A SEM may be equipped with an EDX analysis system to enable it to perform compositional analysis on specimens. EDX analysis is useful in identifying materials and contaminants, as well as estimating their relative concentrations on the surface of the specimen.

SEM - scanning electron microscopy

1.1 Characteristic Information: SEM

Topography

The surface features of an object or "how it looks", its texture; direct relation between these features and materials properties

Morphology The shape and size of the particles making up the object; direct relation between these structures and materials properties

Composition

The elements and compounds that the object is composed of and the relative amounts of them; direct relationship between composition and materials properties

Crystallographic Information

How the atoms are arranged in the object; direct relation between these arrangements and material properties

SEM - scanning electron microscopy



SEM - scanning electron microscopy

Advantages of Using SEM over OM					
Mag OM: 4x - 1400x SEM: 10x - 500Kx	Depth of Field 0.5mm 30mm	Resolution ~ 0.2mm 1.5nm			
The SEM has a larg amount of the san produces an image three-dimensional s	ple to be in focu that is a good re	s at one time and			
The combination of field, greater crystallographic inf most heavily used research areas and i	resolution, con ormation makes th instruments in ac	mpositional and e SEM one of the			

SEM - scanning electron microscopy



1) The "Virtual Source" at the top represents the electron gun, producing a stream of monochromatic electrons.

2) The stream is condensed by the first condenser lens (usually controlled by the coarse probe current knob"). This lens is used to both form the beam and limit the amount of current in the beam. It works in conjunction with the condenser aperture to eliminate the high-angle electrons from the beam.

SEM - scanning electron microscopy



SEM - scanning electron microscopy



Scanning Electron Microscope 6) A set of coils then "scan" or "sweep" the beam in a grid fashion (like a television), dwelling on points for a period of time determined by the scan speed (usually in the microsecond range). 7) The final lens, the objective, focuses the scanning beam onto the part of the specimen desired. 8) When the beam strikes the sample (and dwells for a few microseconds) interactions occur inside the sample and are detected with various instruments. 27

SEM - scanning electron microscopy



How do we get an image?



· In brief: we shoot high-energy electrons and analyze the outcoming electrons/x-rays

Electron beam-sample interactions

- The incident electron beam is scattered in the sample, both elastically and inelastically
- This gives rise to various signals that we can detect (more on that on next slide)
- Interaction volume increases with increasing acceleration voltage and decreases with increasing atomic number



Signals from the sample



Where does the signals come from?



Secondary electrons (SE)

- Generated from the collision between the incoming electrons and the loosely bonded outer electrons
- Low energy electrons (~10-50 eV)
- Only SE generated close to surface escape (topographic information is obtained)
- Number of SE is greater than the number of incoming electrons
- We differentiate between SE1 and SE2



SEM - scanning electron microscopy



Why do we need vacuum?

- Chemical (corrosion!!) and thermal stability is necessary for a well-functioning filament (gun pressure)
 - A field emission gun requires $^{\sim}$ 10 $^{-10}$ Torr LaB_6: $^{\sim}$ 10 $^{-6}$ Torr
- The signal electrons must travel from the sample to the detector (chamber pressure)
 - Vacuum requirements is dependent of the type of detector

SEM - scanning electron microscopy



SEM - scanning electron microscopy



SEM - scanning electron microscopy



SEM - scanning electron microscopy



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SEM - scanning electron microscopy



